

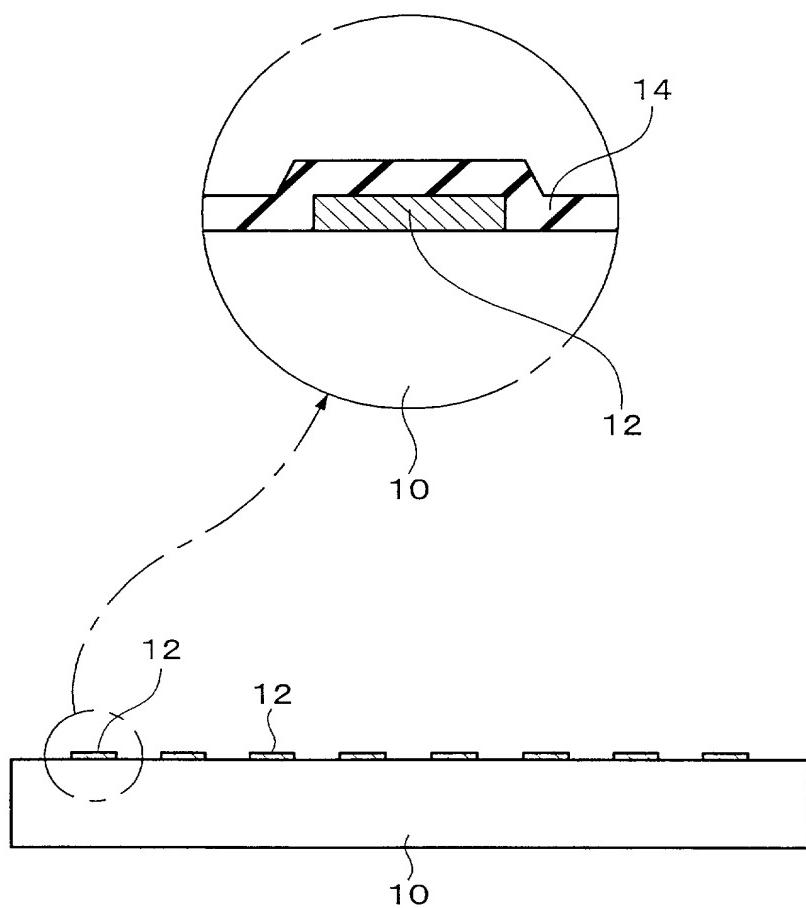
Title: METHOD FOR FORMING A BUMP, SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING SAME, SEMICONDUCTOR CHIP, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

Inventor: Fumiaki MATSUSHIMA

Atty. Ref. No.: 93191-000277

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*FIG. 1*

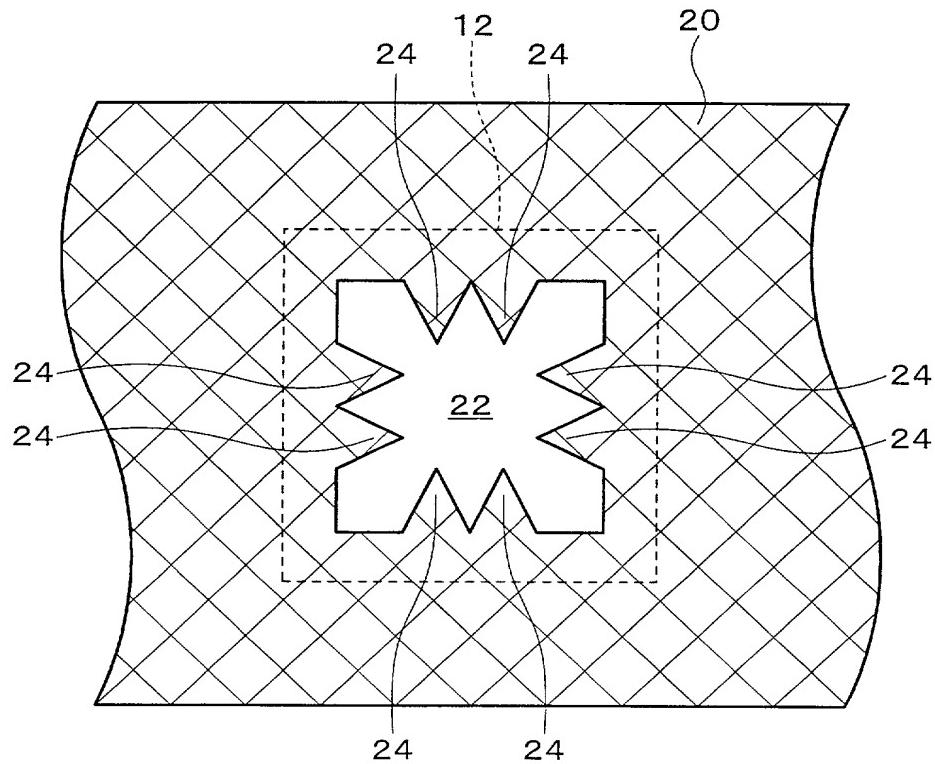


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*FIG. 2*



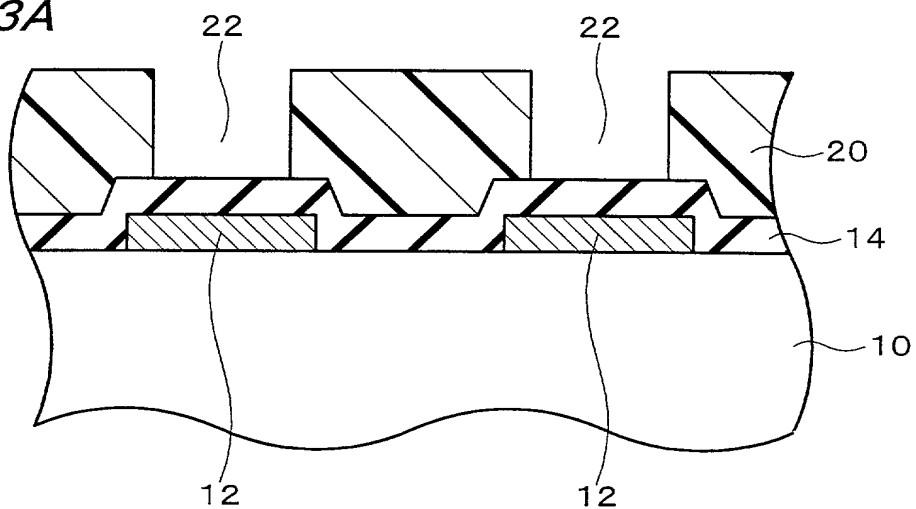
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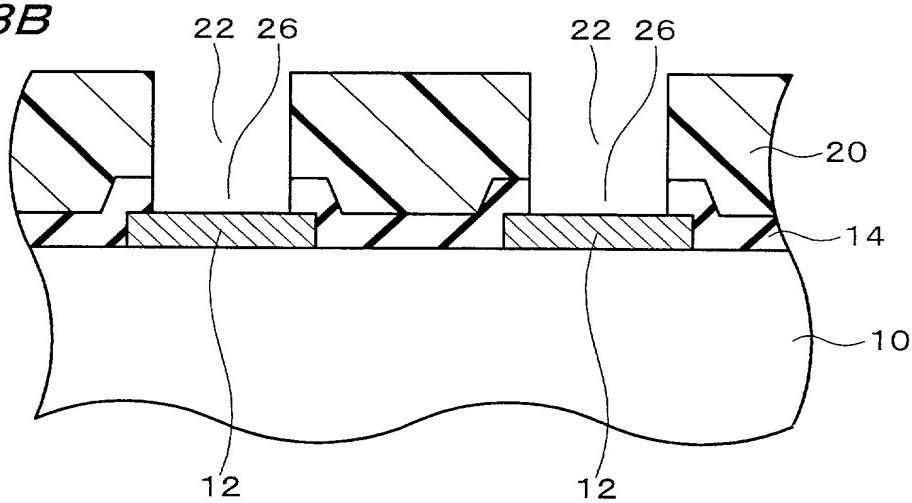
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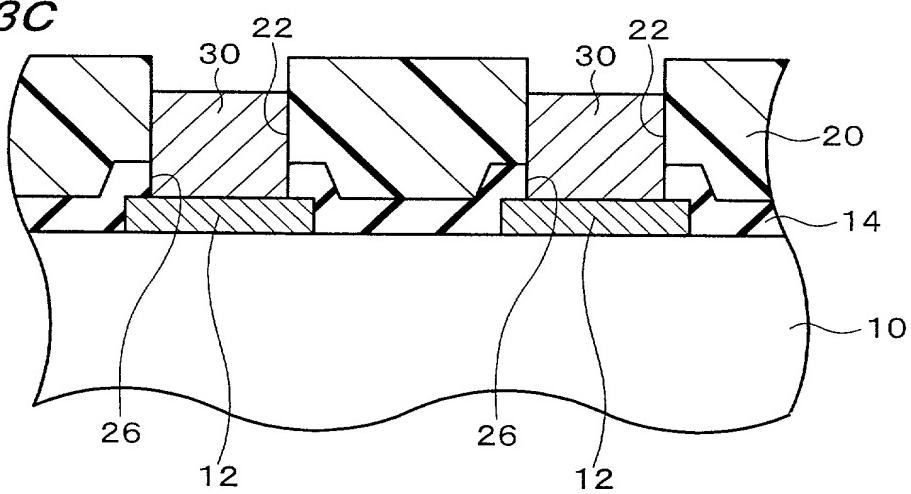
**FIG. 3A**



**FIG. 3B**



**FIG. 3C**



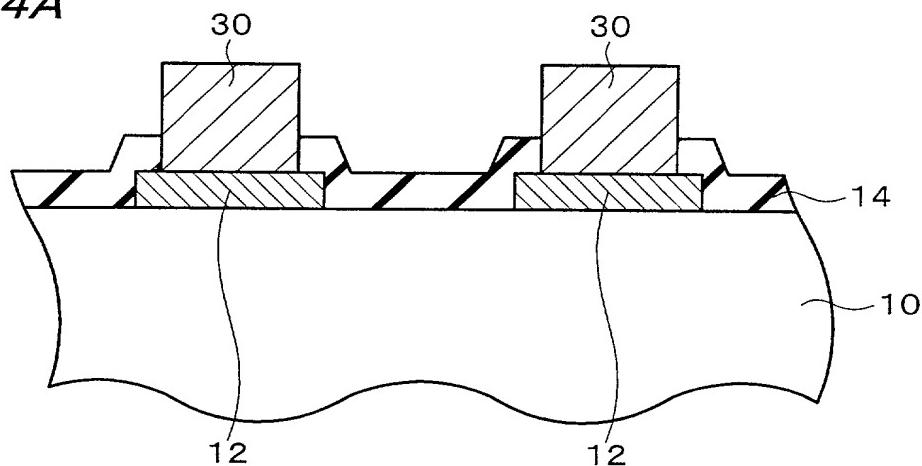
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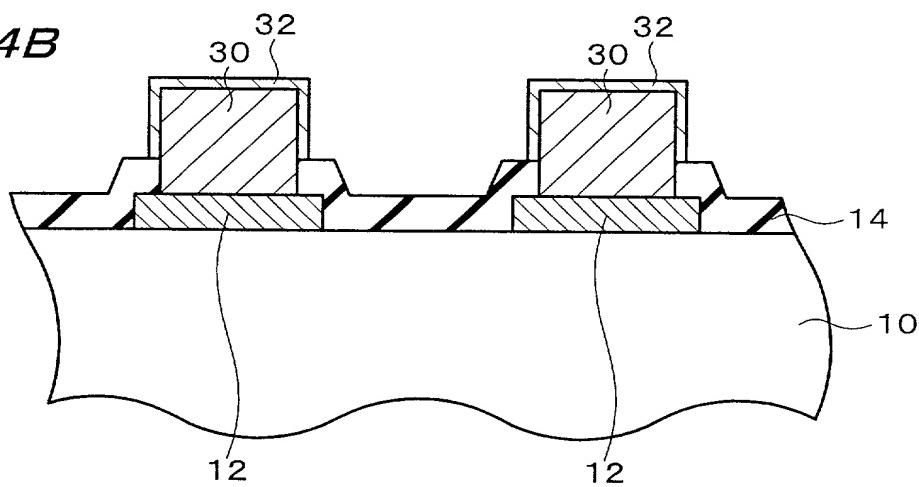
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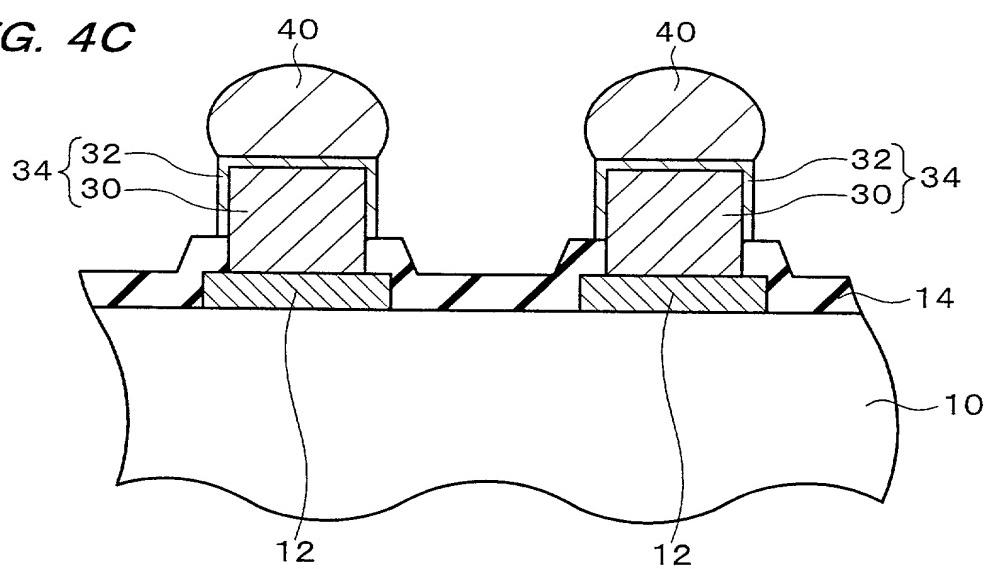
**FIG. 4A**



**FIG. 4B**



**FIG. 4C**



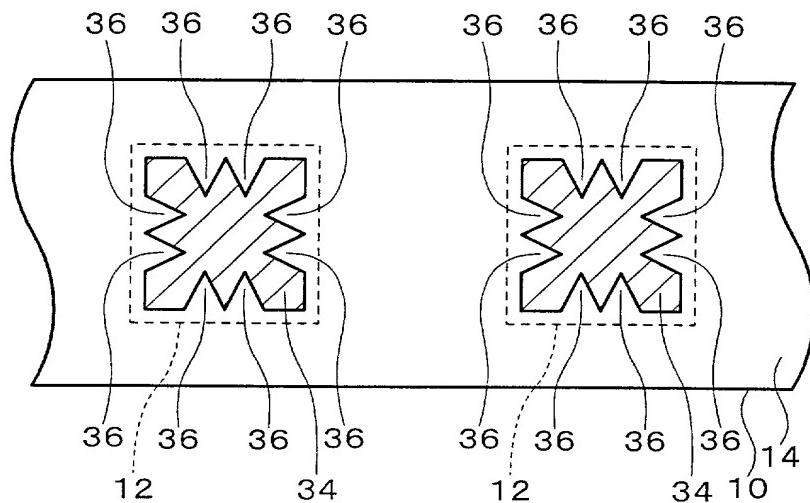
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**FIG. 5**



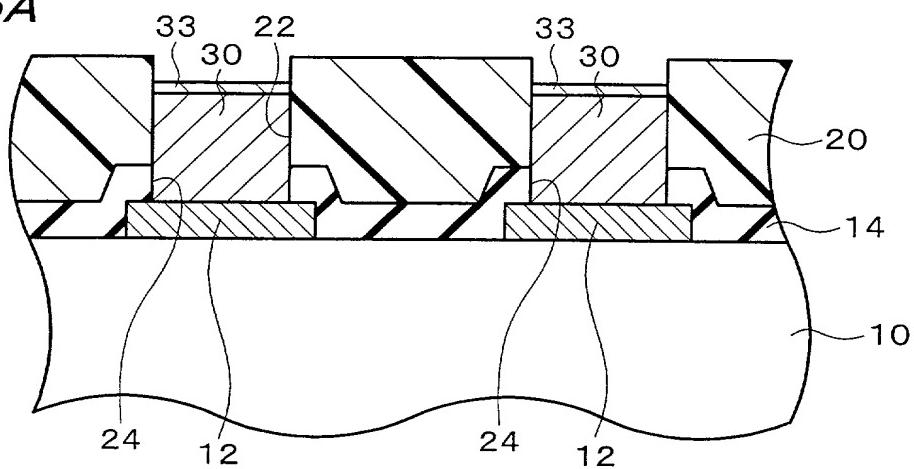
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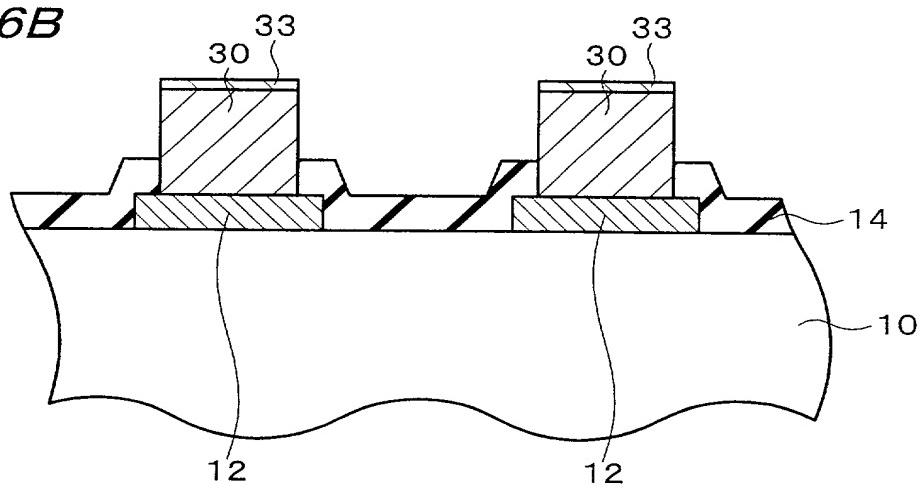
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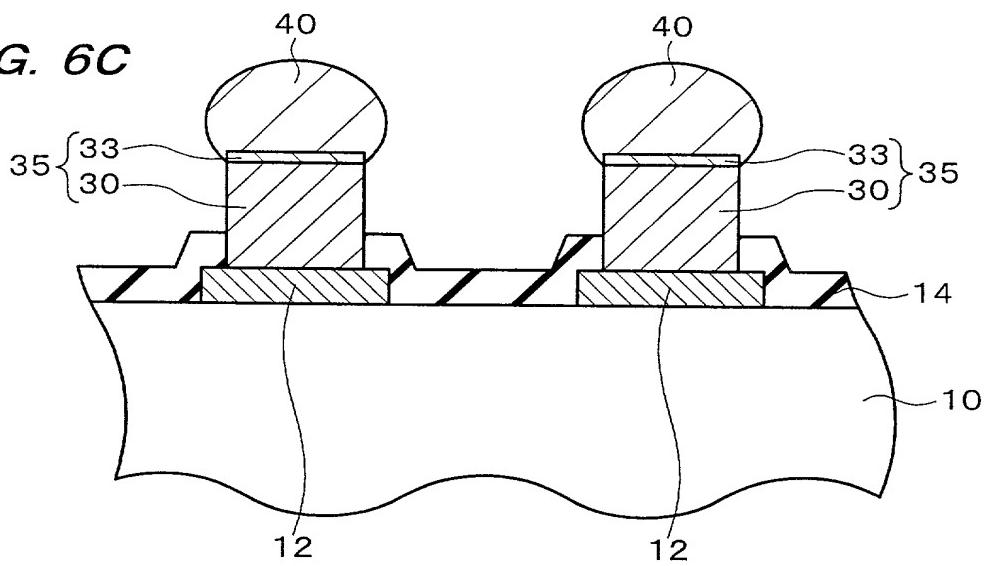
**FIG. 6A**



**FIG. 6B**



**FIG. 6C**



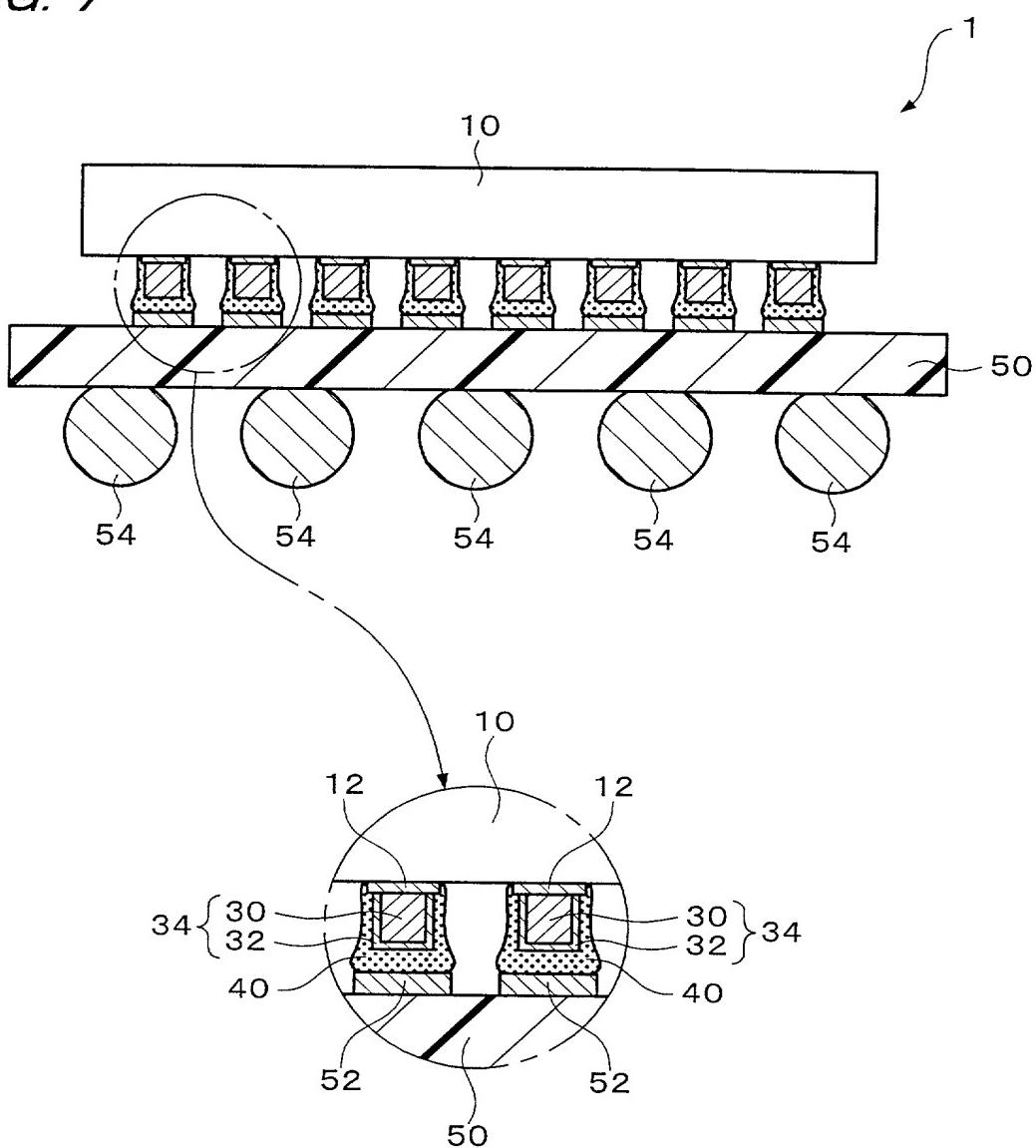
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*FIG. 7*

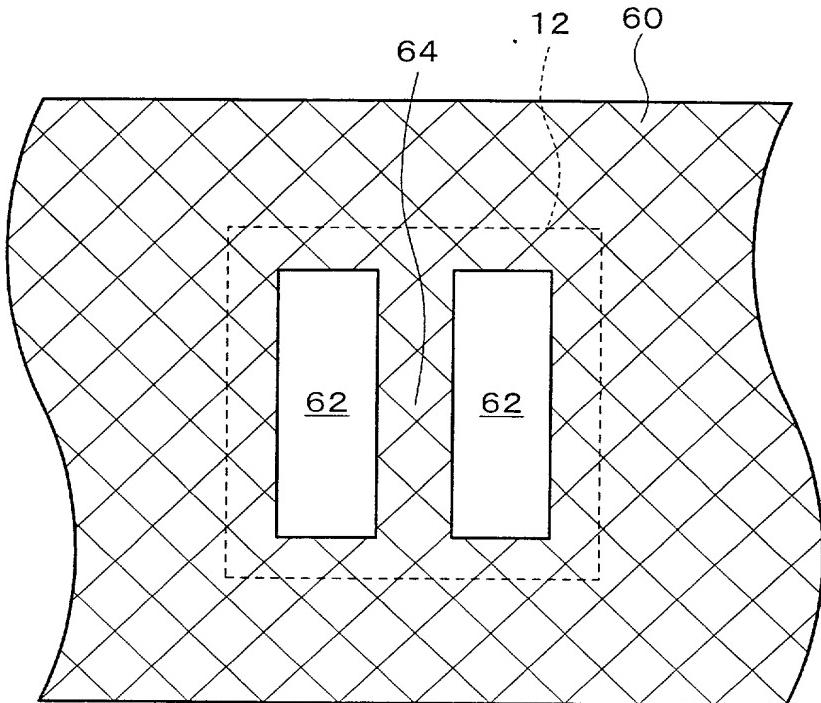


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**FIG. 8**



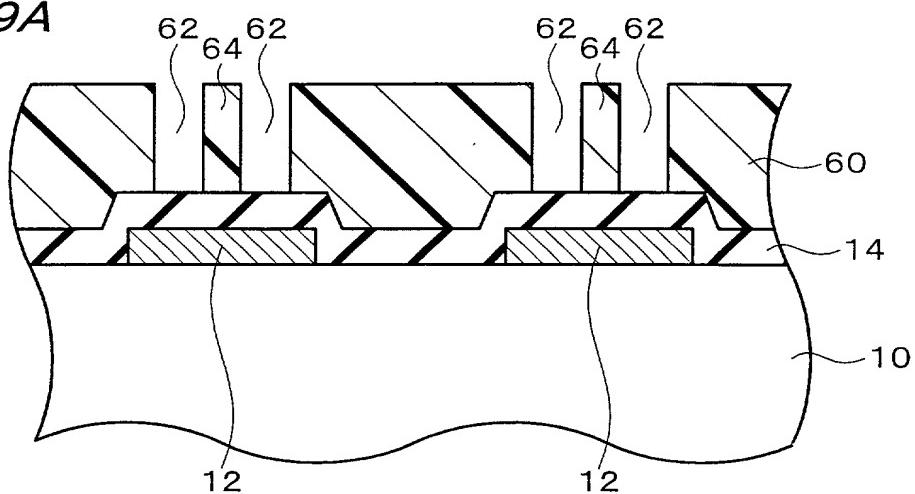
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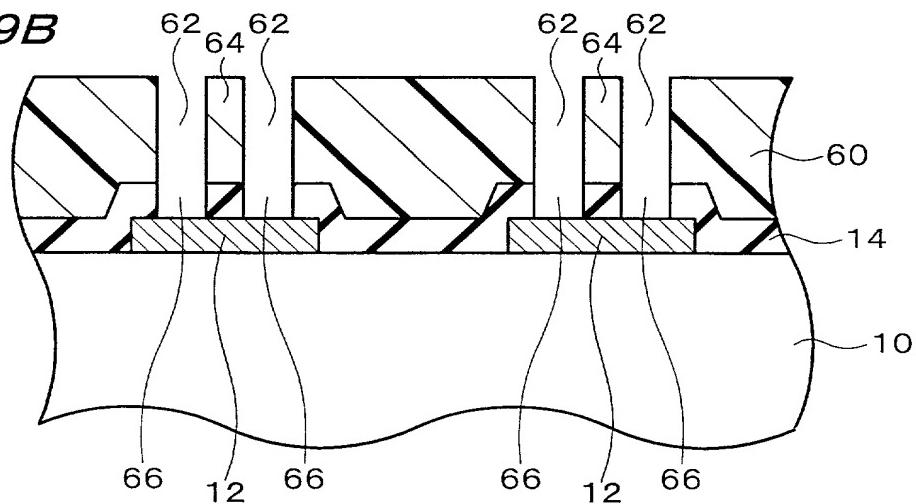
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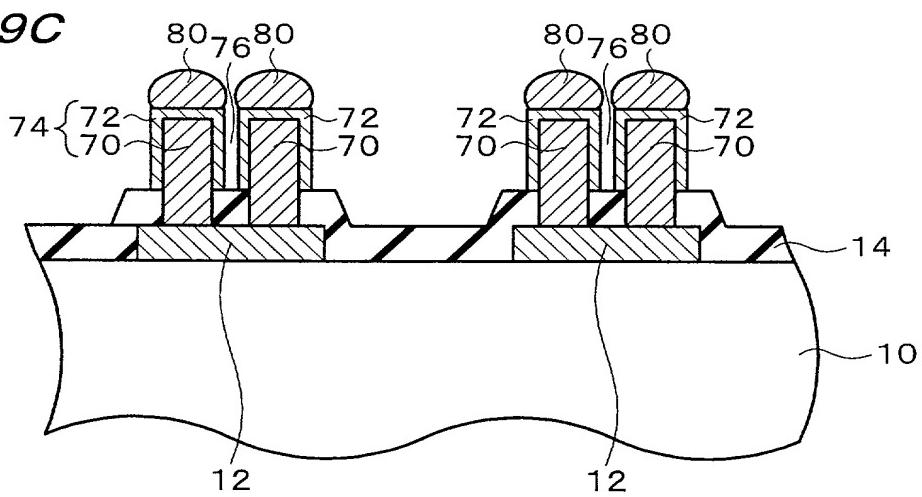
**FIG. 9A**



**FIG. 9B**



**FIG. 9C**



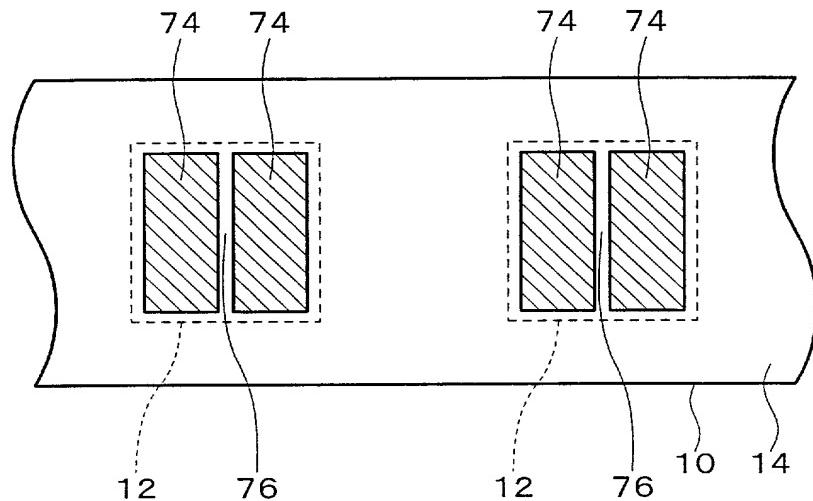
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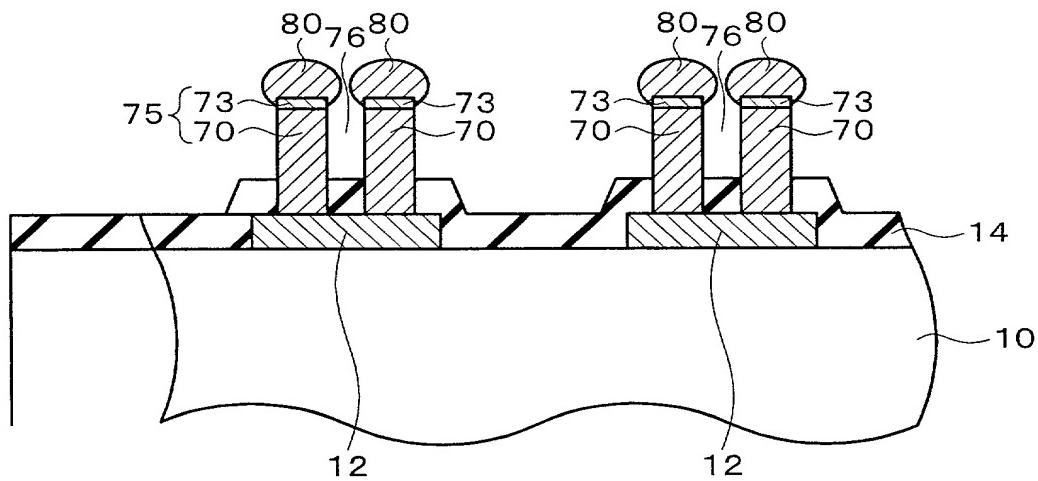
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*FIG. 10*



*FIG. 11*



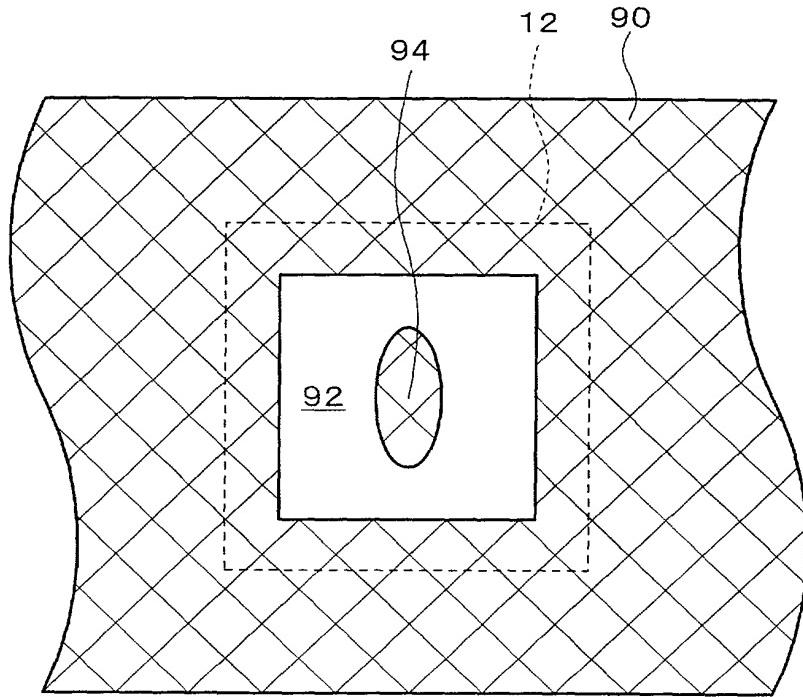
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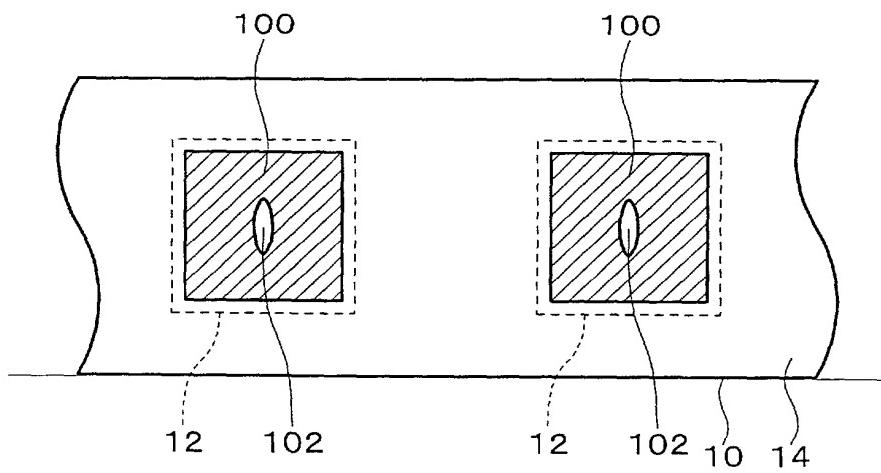
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**FIG. 12A**



**FIG. 12B**



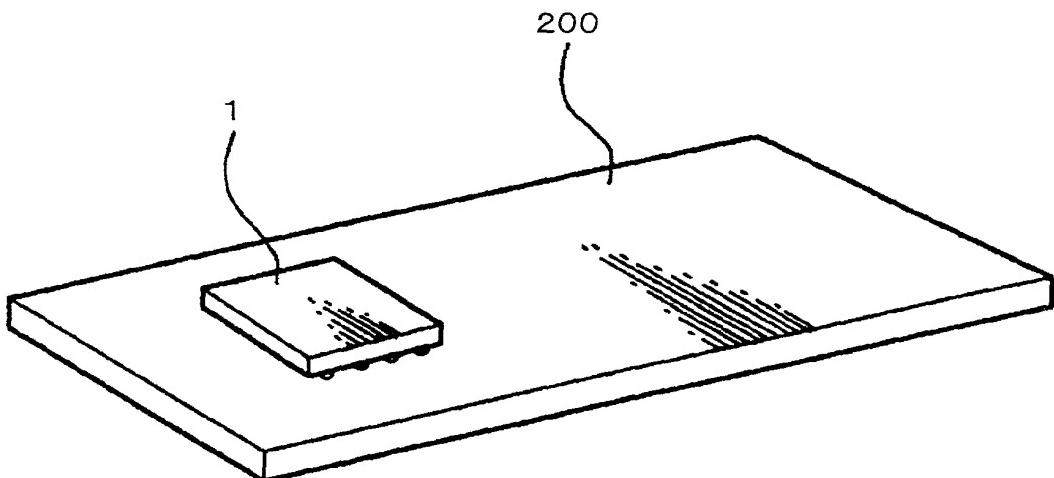
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*FIG. 13*



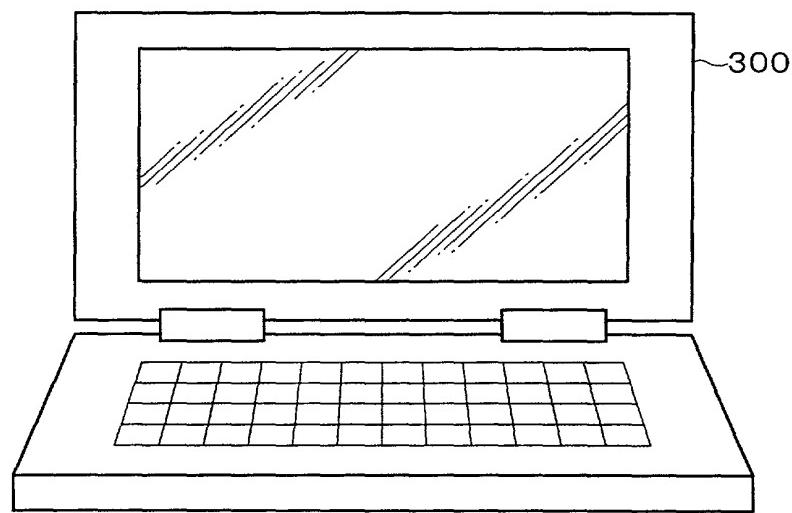
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**FIG. 14**



**FIG. 15**

